



Material Content Data Sheet



Sales Product Name		SAK-TC1767-256F133HL AD		Issued		25. January 2018		
MA#		MA001605746						
Package		PG-LQFP-176-5		Weight*		2008.38 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	38.556	1.92	1.92	19197	19197
leadframe	non noble metal	magnesium	7439-95-4	0.746	0.04		372	
	inorganic material	silicon	7440-21-3	3.234	0.16		1610	
	non noble metal	nickel	7440-02-0	14.925	0.74		7431	
	non noble metal	copper	7440-50-8	478.603	23.83	24.77	238303	247716
wire	noble metal	gold	7440-57-5	7.873	0.39	0.39	3920	3920
encapsulation	organic material	carbon black	1333-86-4	7.227	0.36		3598	
	plastics	epoxy resin	-	195.128	9.72		97157	
	inorganic material	silicondioxide	60676-86-0	1243.036	61.89	71.97	618926	719681
leadfinish	non noble metal	tin	7440-31-5	10.636	0.53	0.53	5296	5296
plating	noble metal	silver	7440-22-4	2.288	0.11	0.11	1139	1139
glue	plastics	epoxy resin	-	1.532	0.08		763	
	noble metal	silver	7440-22-4	4.595	0.23	0.31	2288	3051
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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